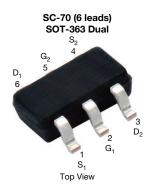
Vishay Siliconix

# **Dual N-Channel 20 V (D-S) MOSFET**



#### Marking code: PE

PRODUCT SUMMARY				
V <sub>DS</sub> (V)	20			
$R_{DS(on)}$ max. ( $\Omega$ ) at $V_{GS} = 4.5 \text{ V}$	0.235			
$R_{DS(on)}$ max. ( $\Omega$ ) at $V_{GS} = 2.5 \text{ V}$	0.306			
Q <sub>g</sub> typ. (nC)	0.9			
I <sub>D</sub> (A) <sup>a</sup>	1.1			
Configuration	Dual			

#### **FEATURES**

- TrenchFET® power MOSFET
- 100 % R<sub>g</sub> tested

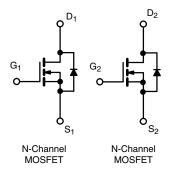




ROHS COMPLIANT HALOGEN FREE

## **APPLICATIONS**

- Load switch and DC/DC converter for portable devices
- · High speed switching



ORDERING INFORMATION	
Package	SC-70
Lead (Pb)-free and halogen-free	Si1902CDL-T1-GE3

PARAMETER		SYMBOL	LIMIT	UNIT	
Drain-source voltage		V <sub>DS</sub>	20	V	
Gate-source voltage		V <sub>GS</sub>	± 12	v	
Continuous drain current (T <sub>J</sub> = 150 °C)	T <sub>C</sub> = 25 °C		1.1		
	T <sub>C</sub> = 70 °C		0.9		
	T <sub>A</sub> = 25 °C	I <sub>D</sub>	1 b, c		
	T <sub>A</sub> = 70 °C		0.8 b, c	А	
Pulsed drain current (t = 300 μs)		I <sub>DM</sub>	2		
Continuous source-drain diode current	T <sub>C</sub> = 25 °C		0.35		
	T <sub>A</sub> = 25 °C	I <sub>S</sub>	0.25 b, c		
Maximum power dissipation	T <sub>C</sub> = 25 °C		0.42		
	T <sub>C</sub> = 70 °C	_	0.27		
	T <sub>A</sub> = 25 °C	P <sub>D</sub>	0.30 b, c	W	
	T <sub>A</sub> = 70 °C		0.23 b, c		
Operating junction and storage temperature ra	ange	T <sub>J</sub> , T <sub>stq</sub>	-55 to +150	°C	

THERMAL RESISTANCE RATINGS						
PARAMETER		SYMBOL	TYPICAL	MAXIMUM	UNIT	
Maximum junction-to-ambient b, d	t ≤ 5 s	R <sub>thJA</sub>	290	350	°C/W	
Maximum junction-to-foot (drain)	Steady state	R <sub>thJF</sub>	250	300		

#### Notes

- a. Based on T<sub>C</sub> = 25 °C
- b. Surface mounted on 1" x 1" FR4 board
- c. t = 5 s
- d. Maximum under steady state conditions is 410  $^{\circ}\text{C/W}$



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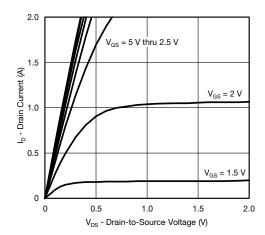
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT
Static					•	
Drain-source breakdown voltage	$V_{DS}$	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$	20	-	-	V
V <sub>DS</sub> temperature coefficient	$\Delta V_{DS}/T_{J}$	J 050 ·· A	-	25	-	mV/°C
V <sub>GS(th)</sub> temperature coefficient	$\Delta V_{GS(th)}/T_J$	I <sub>D</sub> = 250 μA	-	-2.6	-	
Gate-source threshold voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_D = 250 \mu A$	0.6	-	1.5	V
Gate-source leakage	I <sub>GSS</sub>	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 12 \text{ V}$	-	-	± 100	nA
Zana mata walta na aluaina awanant		V <sub>DS</sub> = 20 V, V <sub>GS</sub> = 0 V	-	-	1	μА
Zero gate voltage drain current	I <sub>DSS</sub>	V <sub>DS</sub> = 20 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 85 °C	-	-	10	
On-state drain current a	I <sub>D(on)</sub>	$V_{DS} \ge 5 \text{ V}, V_{GS} = 4.5 \text{ V}$	2	-	-	Α
Drain-source on-state resistance a	_	$V_{GS} = 4.5 \text{ V}, I_D = 1 \text{ A}$	-	0.195	0.235	Ω
	R <sub>DS(on)</sub>	$V_{GS} = 2.5 \text{ V}, I_D = 0.3 \text{ A}$	-	0.255	0.306	
Forward transconductance	9 <sub>fs</sub>	$V_{DS} = 10 \text{ V}, I_D = 1 \text{ A}$	-	3	-	ms
Dynamic <sup>b</sup>						
Input capacitance	C <sub>iss</sub>		-	62	-	pF
Output capacitance	C <sub>oss</sub>	$V_{DS} = 10 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$	-	20	-	
Reverse transfer capacitance	C <sub>rss</sub>		-	7	-	
Total colonia de co	0	V <sub>DS</sub> = 10 V, V <sub>GS</sub> = 10 V, I <sub>D</sub> = 1 A	-	2	3	
Total gate charge	$Q_g$		-	0.9	1.4	nC
Gate-source charge	Q <sub>gs</sub>	$V_{DS} = 10 \text{ V}, V_{GS} = 4.5 \text{ V}, I_D = 1 \text{ A}$	-	0.2	-	
Gate-drain charge	Q <sub>gd</sub>		-	0.2	-	
Gate resistance	$R_g$	f = 1 MHz	2.4	12	24	Ω
Turn-on delay time	t <sub>d(on)</sub>		-	4	8	
Rise time	t <sub>r</sub>	$V_{DD} = 10 \text{ V}, R_1 = 12.5 \Omega$	-	13	20	- - -
Turn-off delay time	t <sub>d(off)</sub>	$I_D \cong 0.8 \text{ A}, V_{GEN} = 10 \text{ V}, R_g = 1 \Omega$	-	11	20	
Fall time	t <sub>f</sub>		-	9	18	
Turn-on delay time	t <sub>d(on)</sub>		-	6	12	
Rise time	t <sub>r</sub>	$V_{DD} = 10 \text{ V}, R_{I} = 12.5 \Omega$	-	16	24	ns
Turn-off delay time	t <sub>d(off)</sub>	$I_D \cong 0.8 \text{ A}, V_{GEN} = 4.5 \text{ V}, R_g = 1 \Omega$	-	13	20	
Fall time	t <sub>f</sub>		-	10	20	
<b>Drain-Source Body Diode Characterist</b>	ics		1		•	I
Continuous source-drain diode current	I <sub>S</sub>	T <sub>C</sub> = 25 °C	-	-	0.35	_
Pulse diode forward current <sup>a</sup>	I <sub>SM</sub>	-		-	2	A
Body diode voltage	V <sub>SD</sub>	I <sub>S</sub> = 0.8 A	-	0.8	1.2	V
Body diode reverse recovery time	t <sub>rr</sub>		-	2	4	nC
Body diode reverse recovery charge	Q <sub>rr</sub>		-	8	16	
Reverse recovery fall time	t <sub>a</sub>	$I_F = 0.8 \text{ A}, \text{ di/dt} = 100 \text{ A/}\mu\text{s}$	-	5	-	ns
Reverse recovery rise time	t <sub>b</sub>		-	3	_	

#### Notes

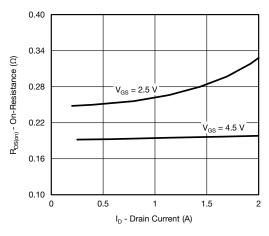
- a. Pulse test; pulse width  $\leq 300~\mu s,\,duty~cycle \leq 2\%$
- b. Guaranteed by design, not subject to production testing

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

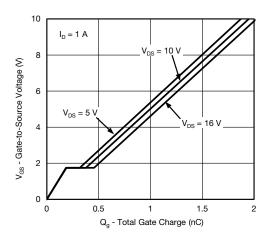




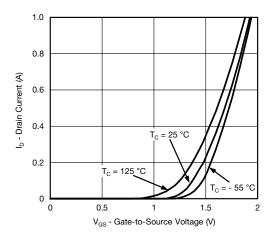
## **Output Characteristics**



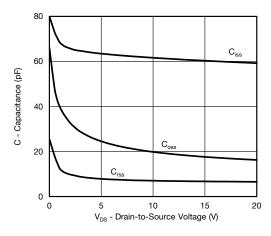
On-Resistance vs. Drain Current and Gate Voltage



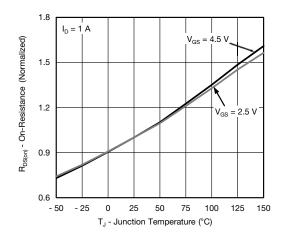
**Gate Charge** 



**Transfer Characteristics** 

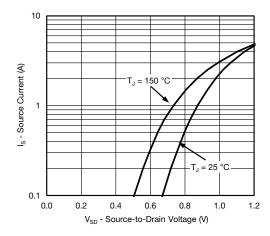


Capacitance

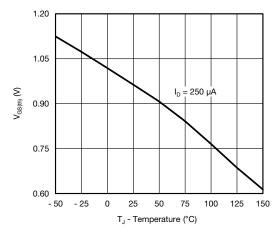


On-Resistance vs. Junction Temperature

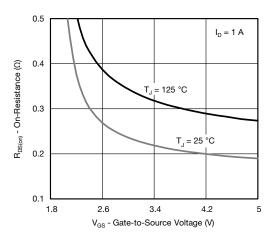




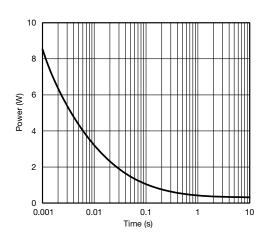
## Source-Drain Diode Forward Voltage



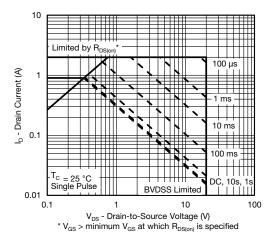
**Threshold Voltage** 



On-Resistance vs. Gate-to-Source Voltage

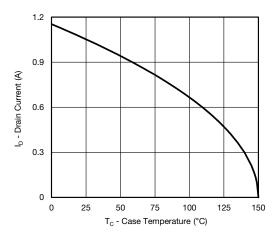


Single Pulse Power (Junction-to-Ambient)

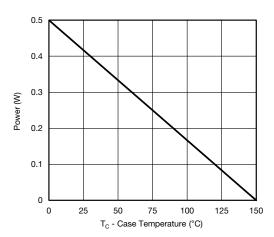


Safe Operating Area, Junction-to-Ambient

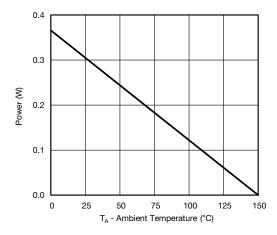




## Current Derating a





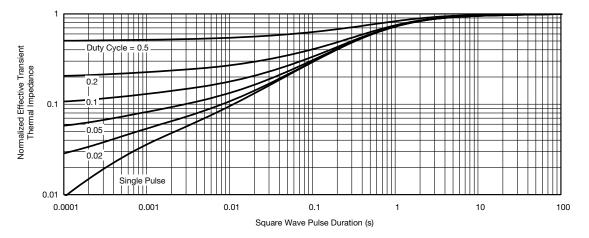


Power Derating, Junction-to-Ambient

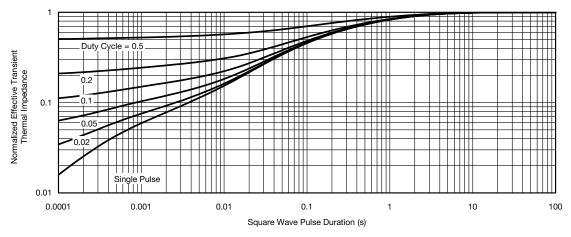
#### Note

a. The power dissipation P<sub>D</sub> is based on T<sub>J</sub> max. = 150 °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit





Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Foot

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